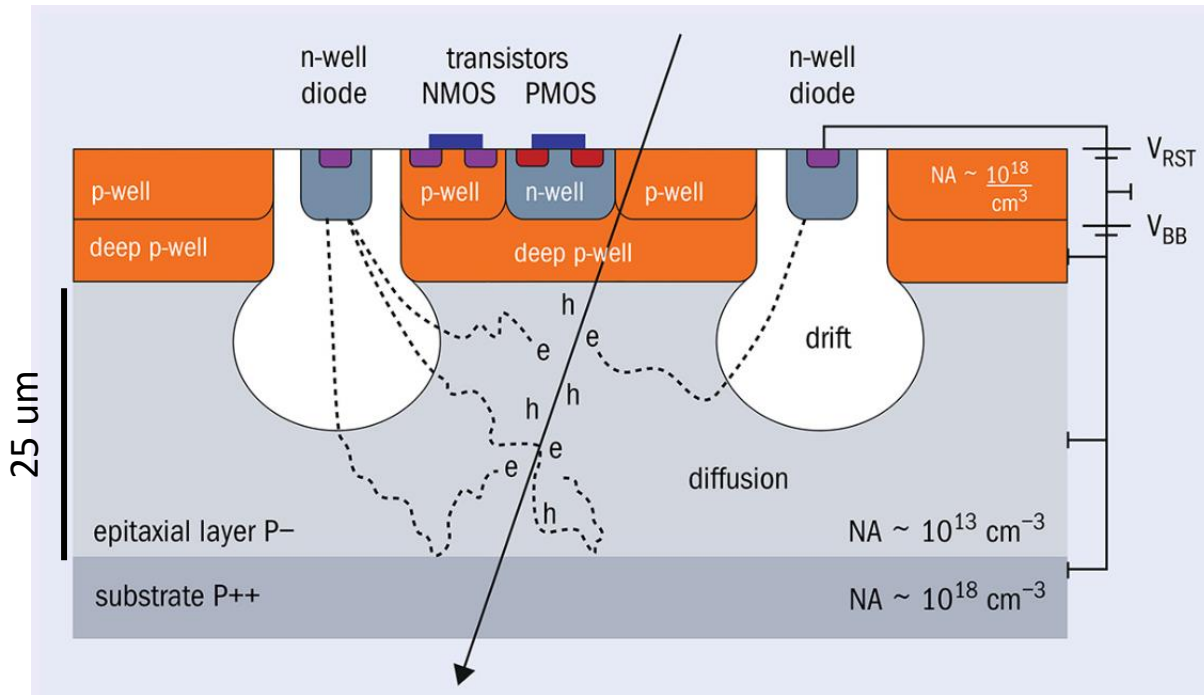


# Overview of Digital Pixel Test Structure (DPTS) studies at LBNL

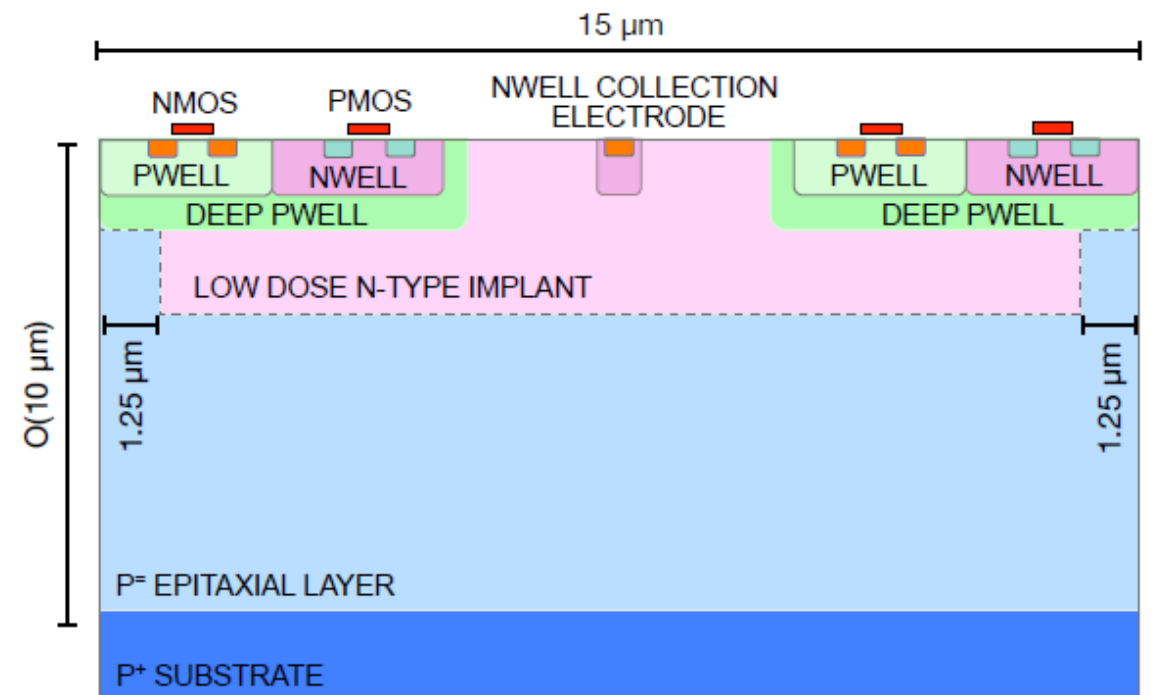
Barak Schmookler

# DPTS chip

## ALPIDE Chip



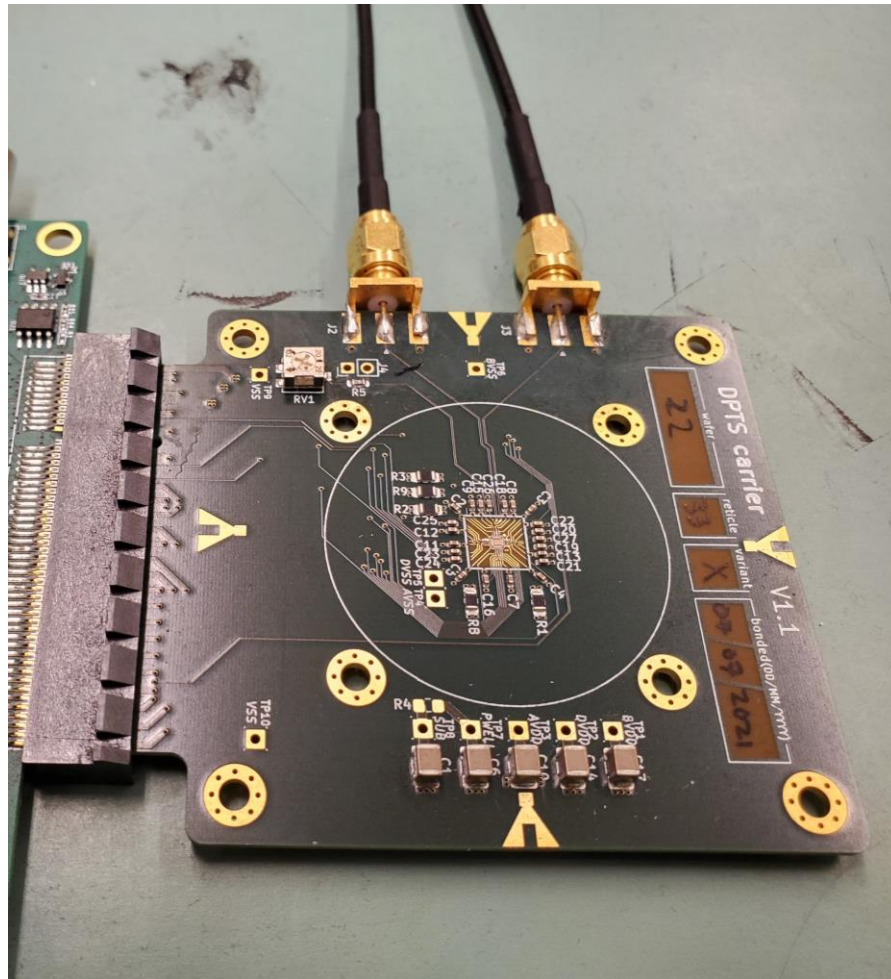
## DPTS Chip



- The most complex prototype MAPS produced in the first submission of the Tower Partners Semiconduction Company 65nm technology process.
- Junction displaced into the epitaxial layer to deplete layer over the full pixel width.

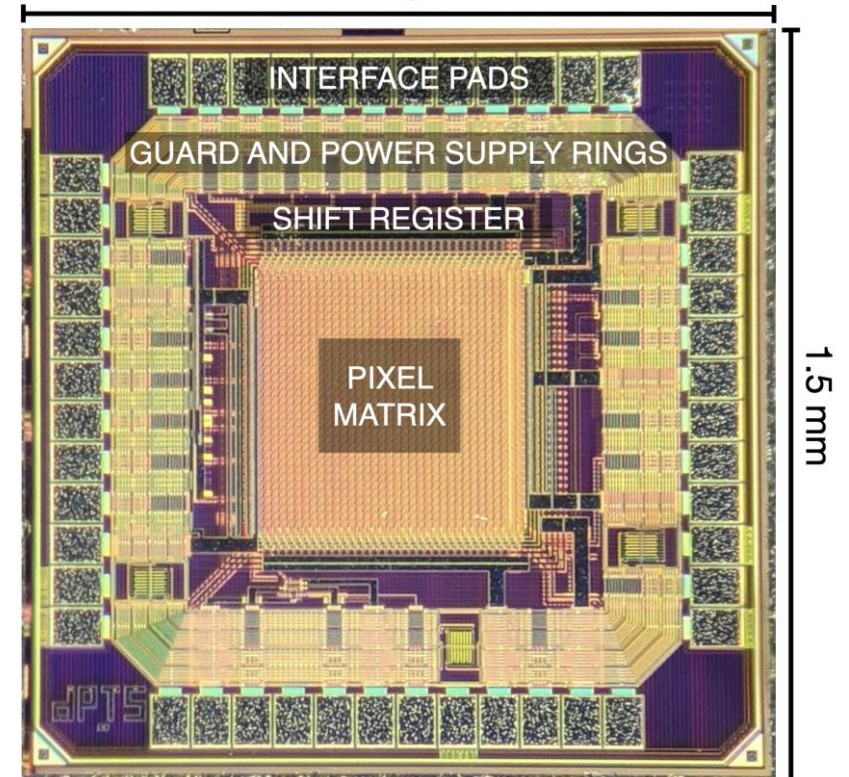
# DPTS chip

Chip on carrier card



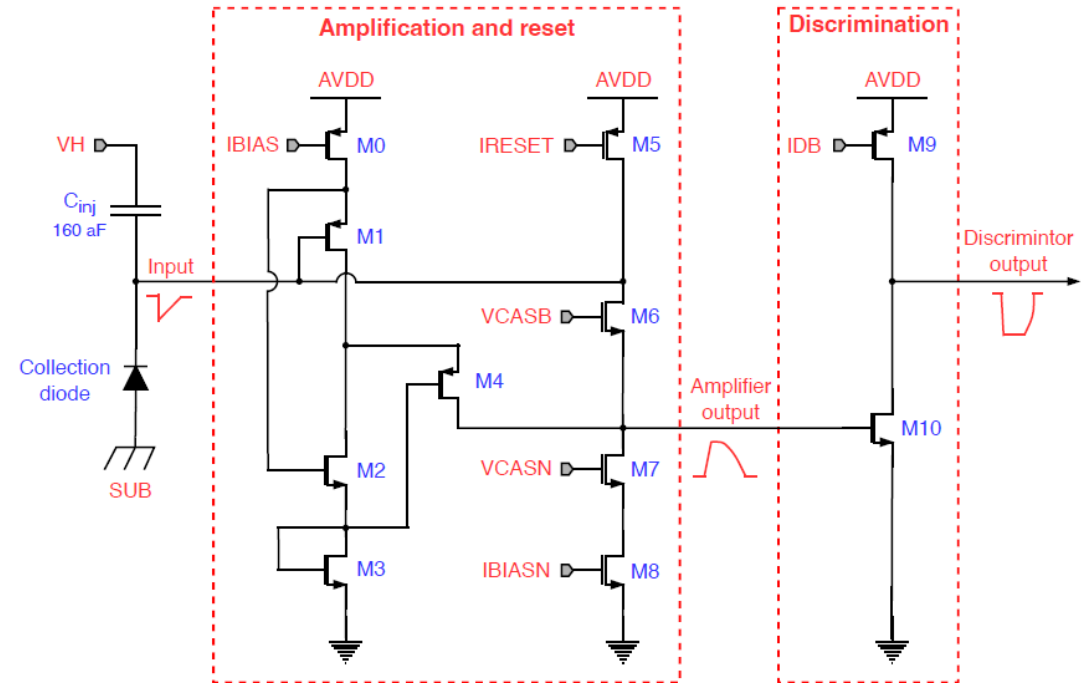
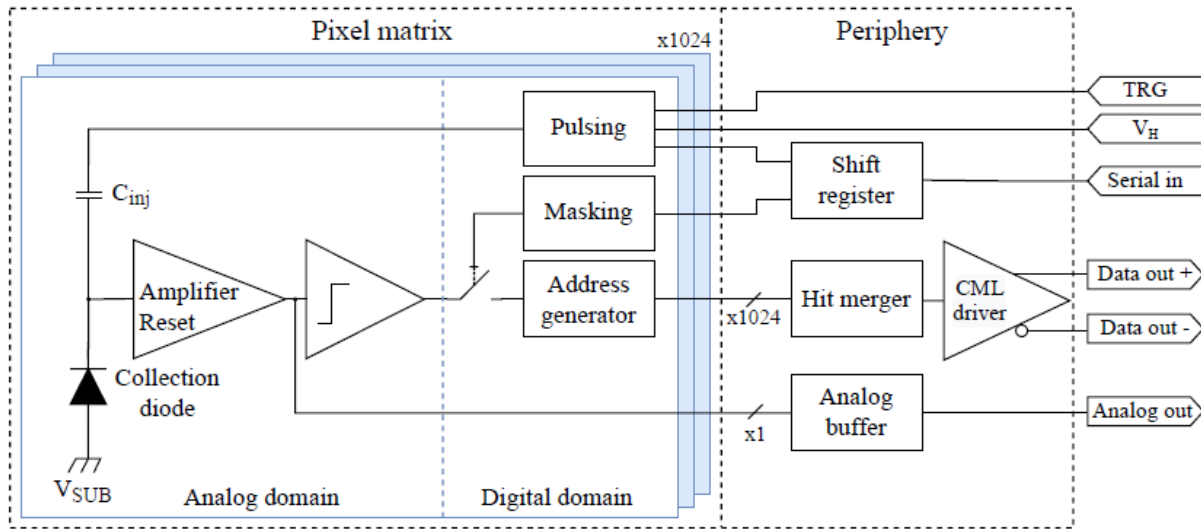
Consists of 32x32 pixel array –  
1024 pixels in total

1.5 mm



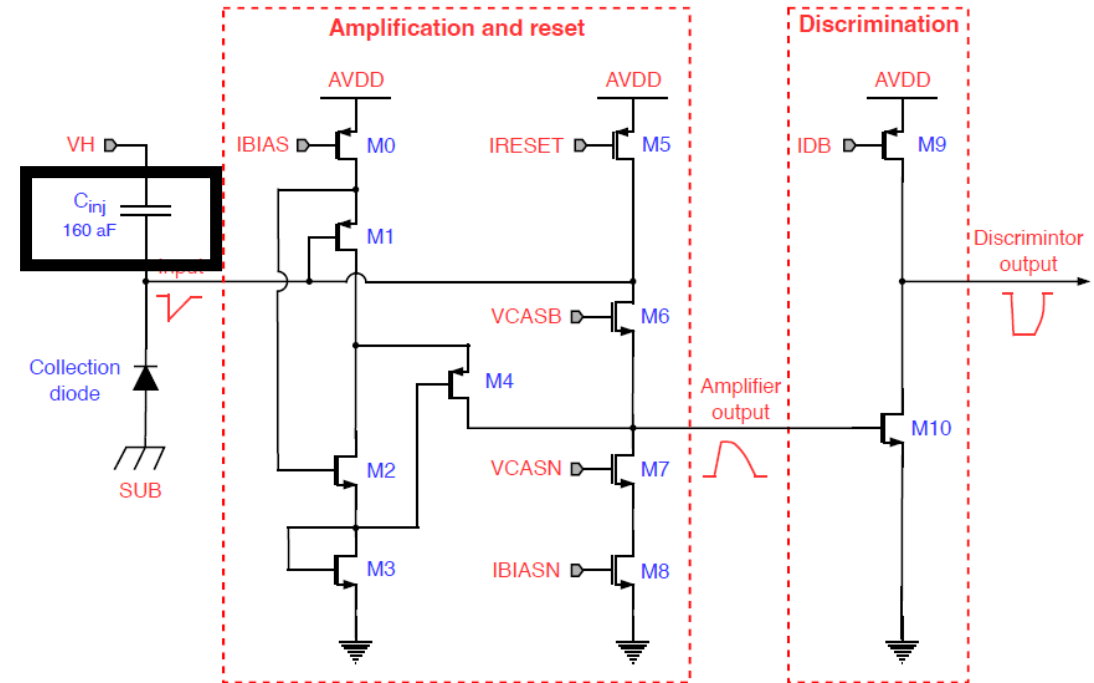
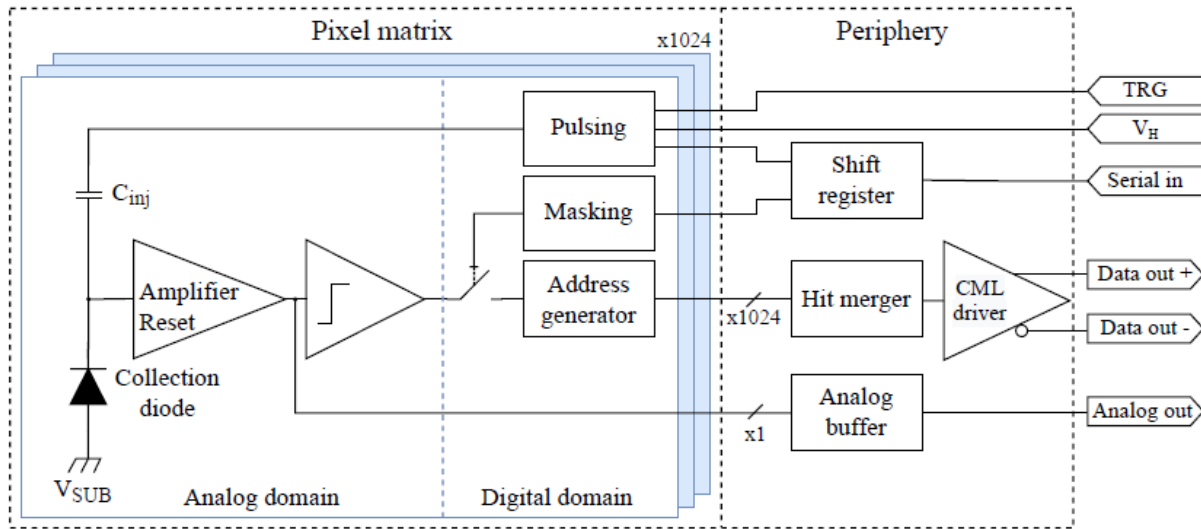
1.5 mm

# DPTS chip



- The DPTS chip is controlled by a set of external reference currents and voltages.
- It is read out via a current mode logic (CML) output.
- The in-pixel front end amplifies, shapes, and discriminates the signal from the collection diode.
- A test circuitry can inject charge into the collection electrode.

# DPTS chip

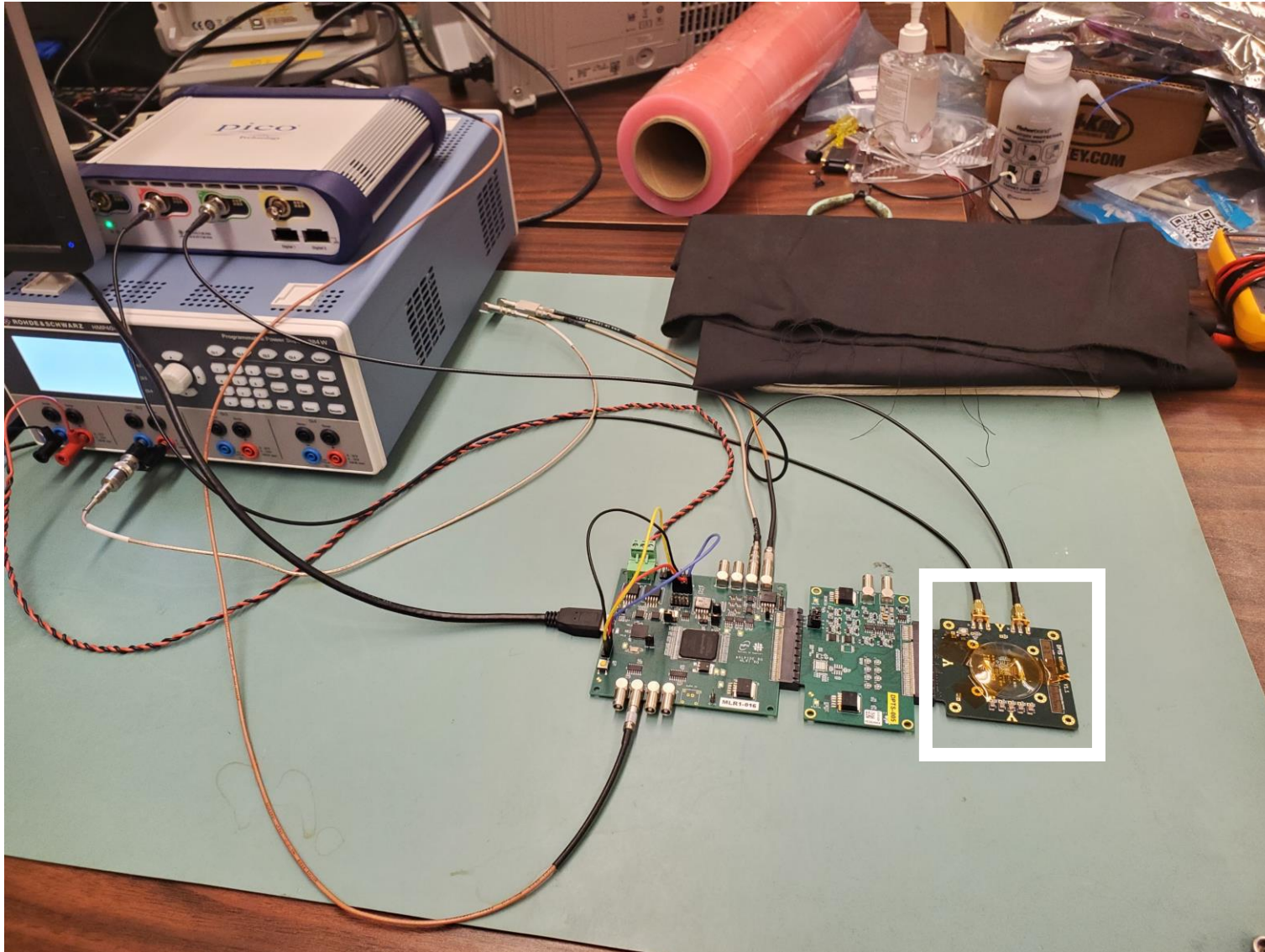


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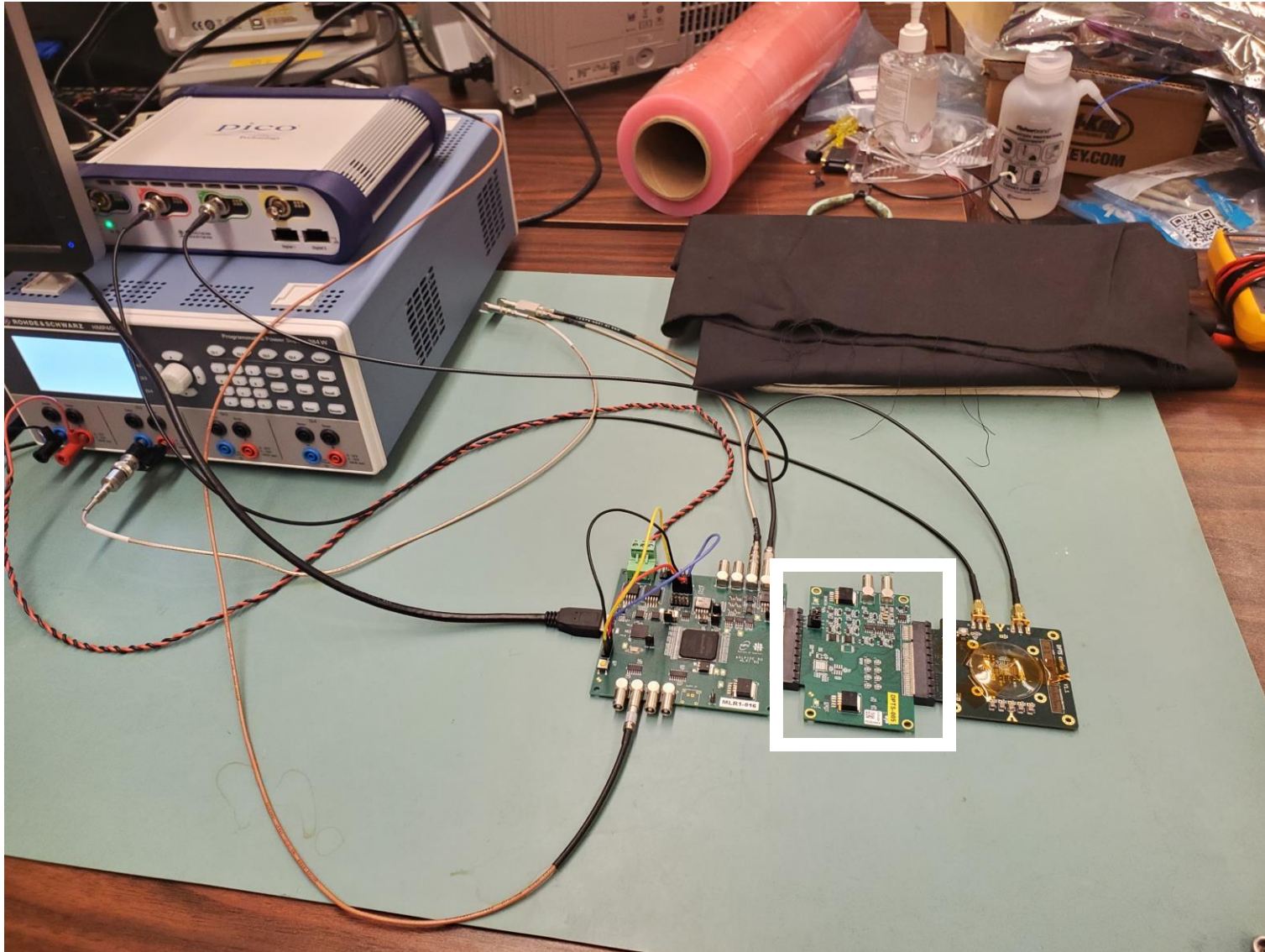


# LBNL bench test setup



1. DPTS chip and carrier card

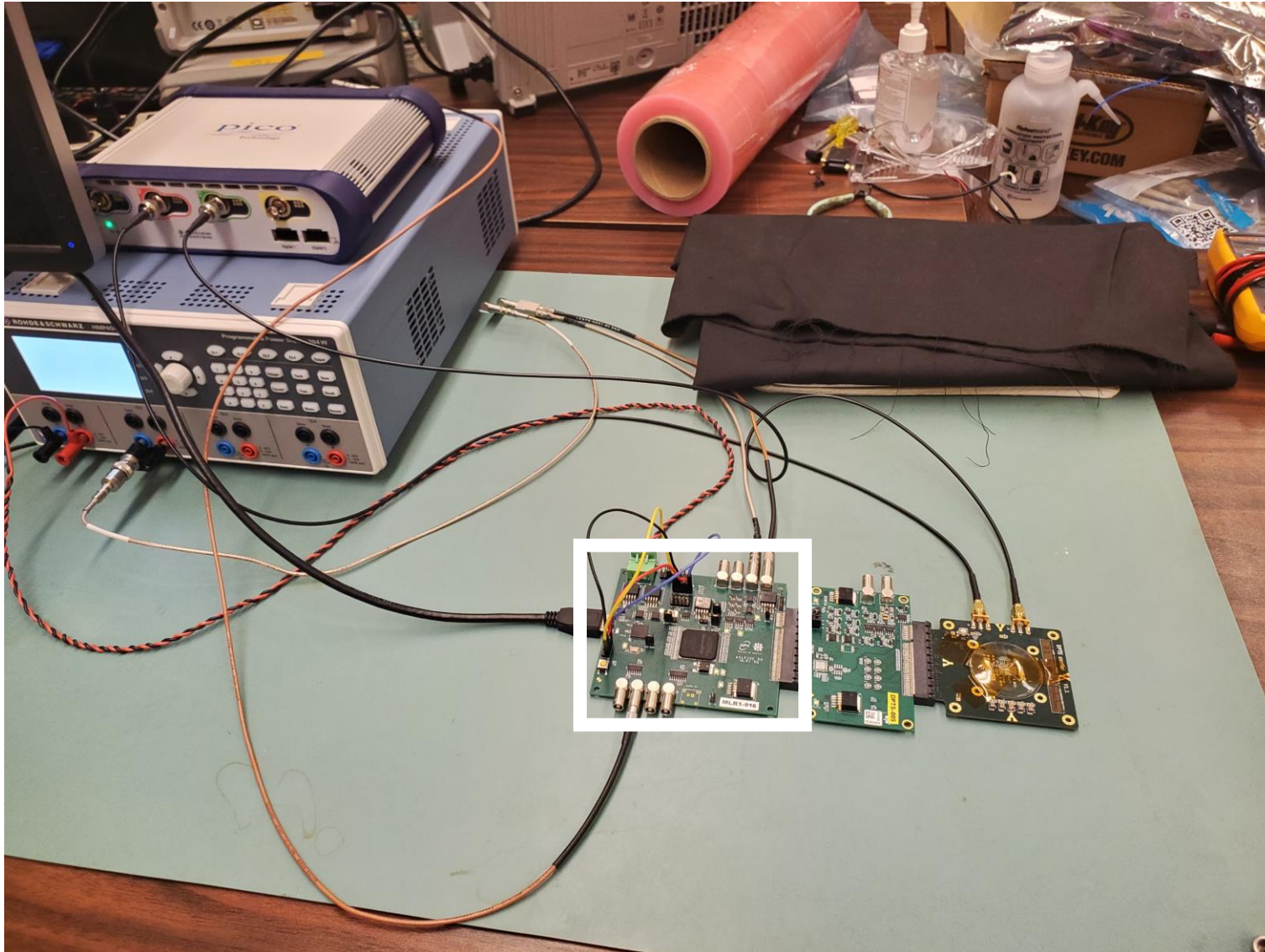
# LBNL bench test setup



1. DPTS chip and carrier card
2. Proximity board



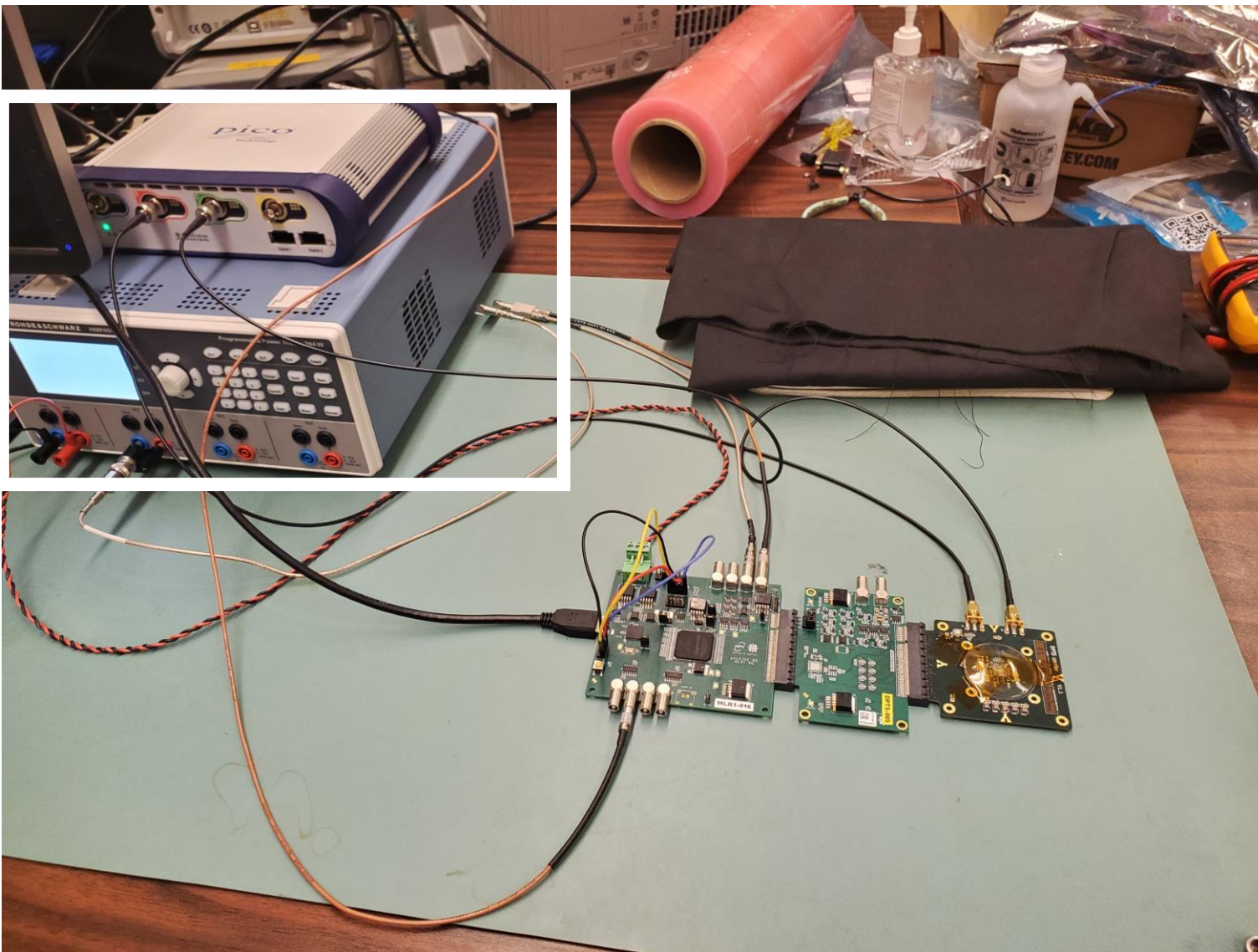
# LBNL bench test setup



1. DPTS chip and carrier card
2. Proximity board
3. MLR1 DAQ board

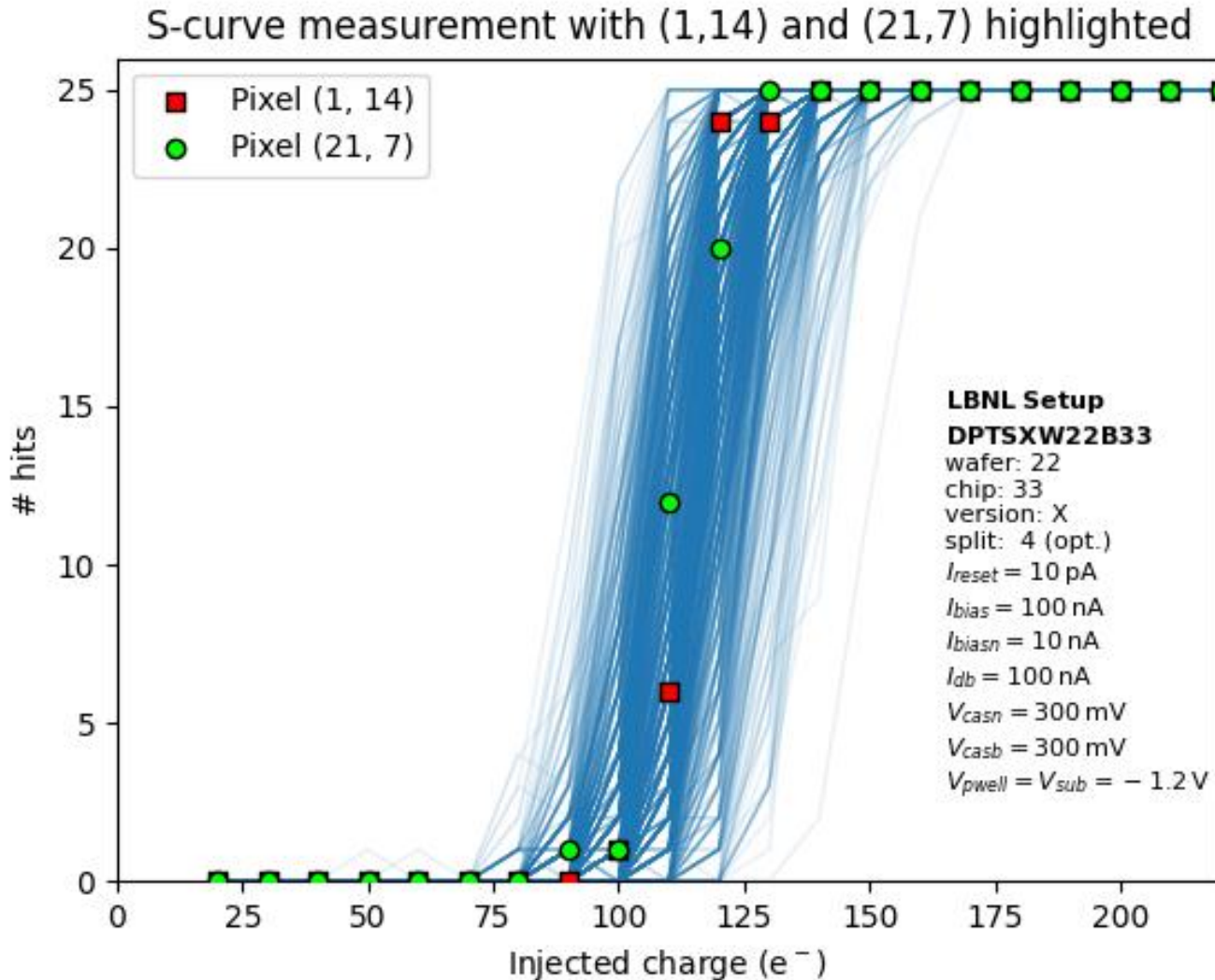


# LBNL bench test setup

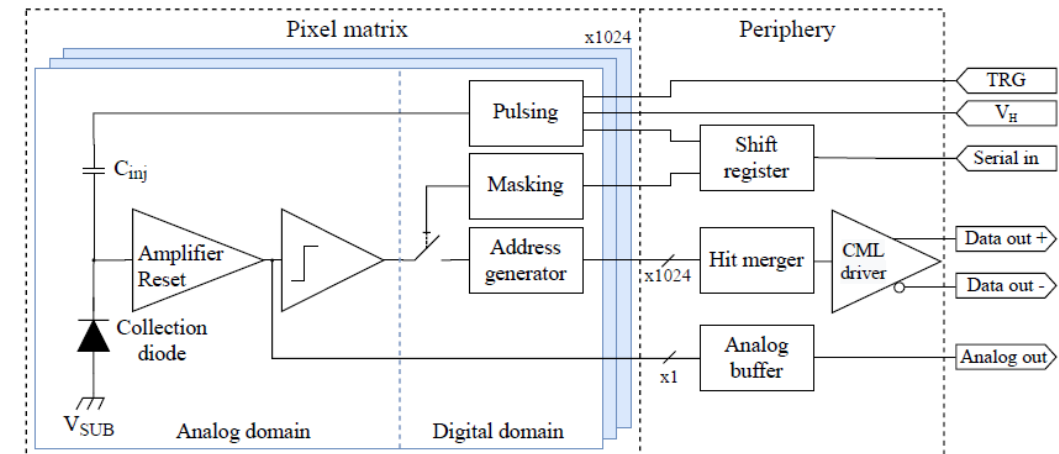


1. DPTS chip and carrier card
2. Proximity board
3. MLR1 DAQ board
4. Power supply and digital oscilloscope

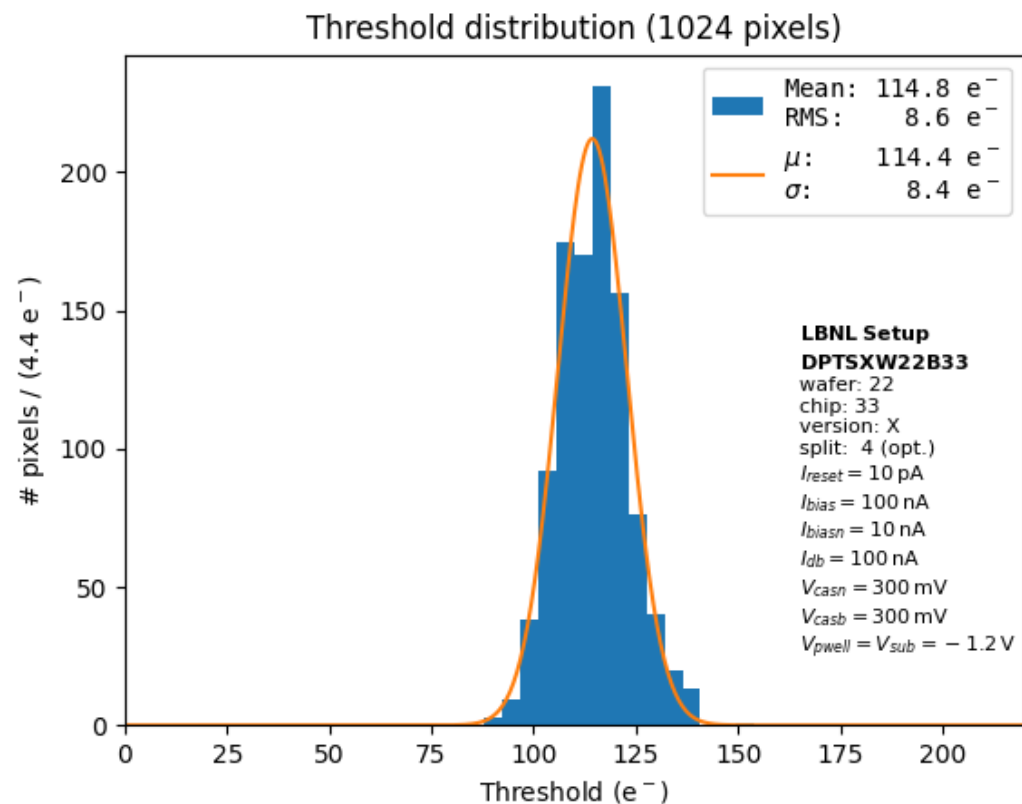
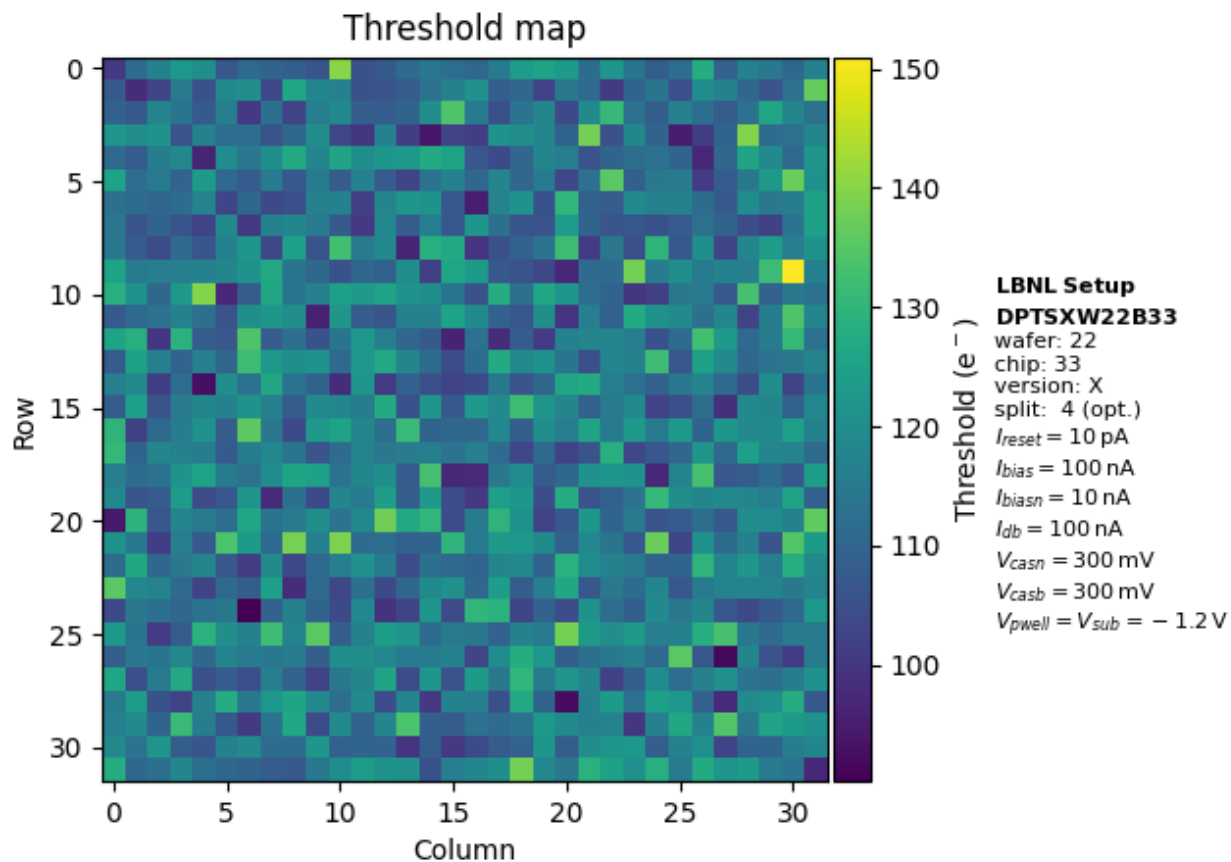
# Threshold scan



At a given  $V_H$  (i.e. injected charge), each pixel is pulsed 25 times and the number of hits is recorded. A hit requires two pulses to be captured by the scope – indicating the assertion and de-assertion of the discriminator pulse.



# Threshold scan

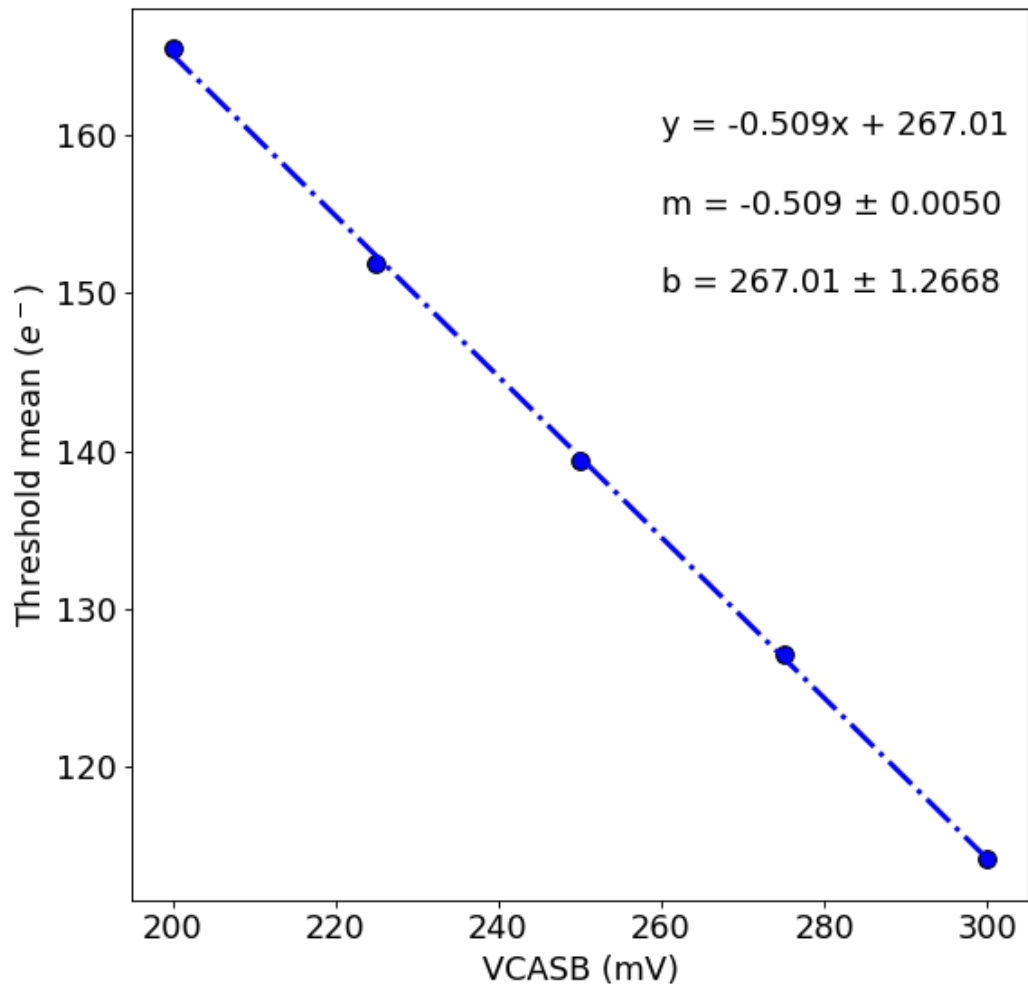


The threshold and noise can be determined from the S-Curve.

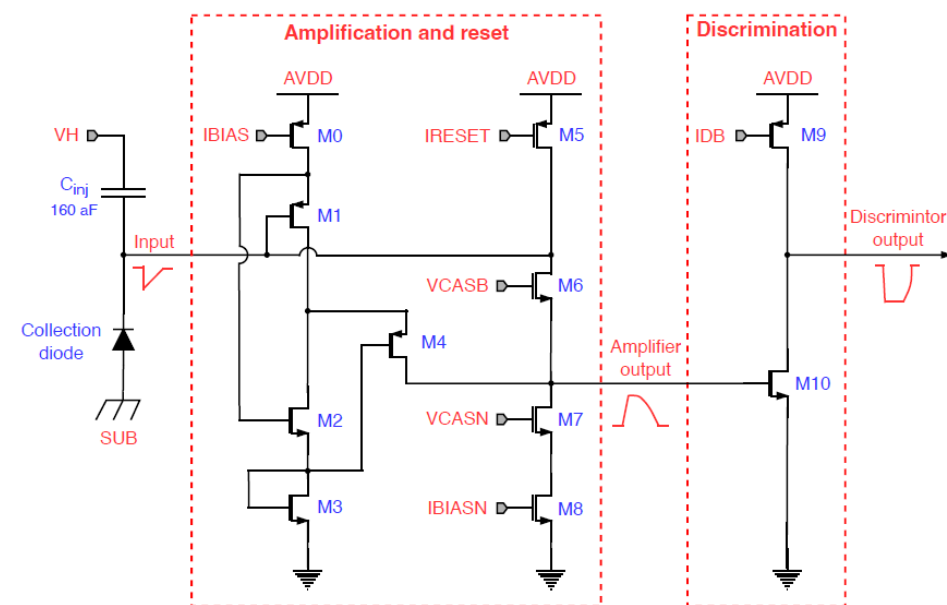


# Threshold scan

VCASB vs. Threshold Mean

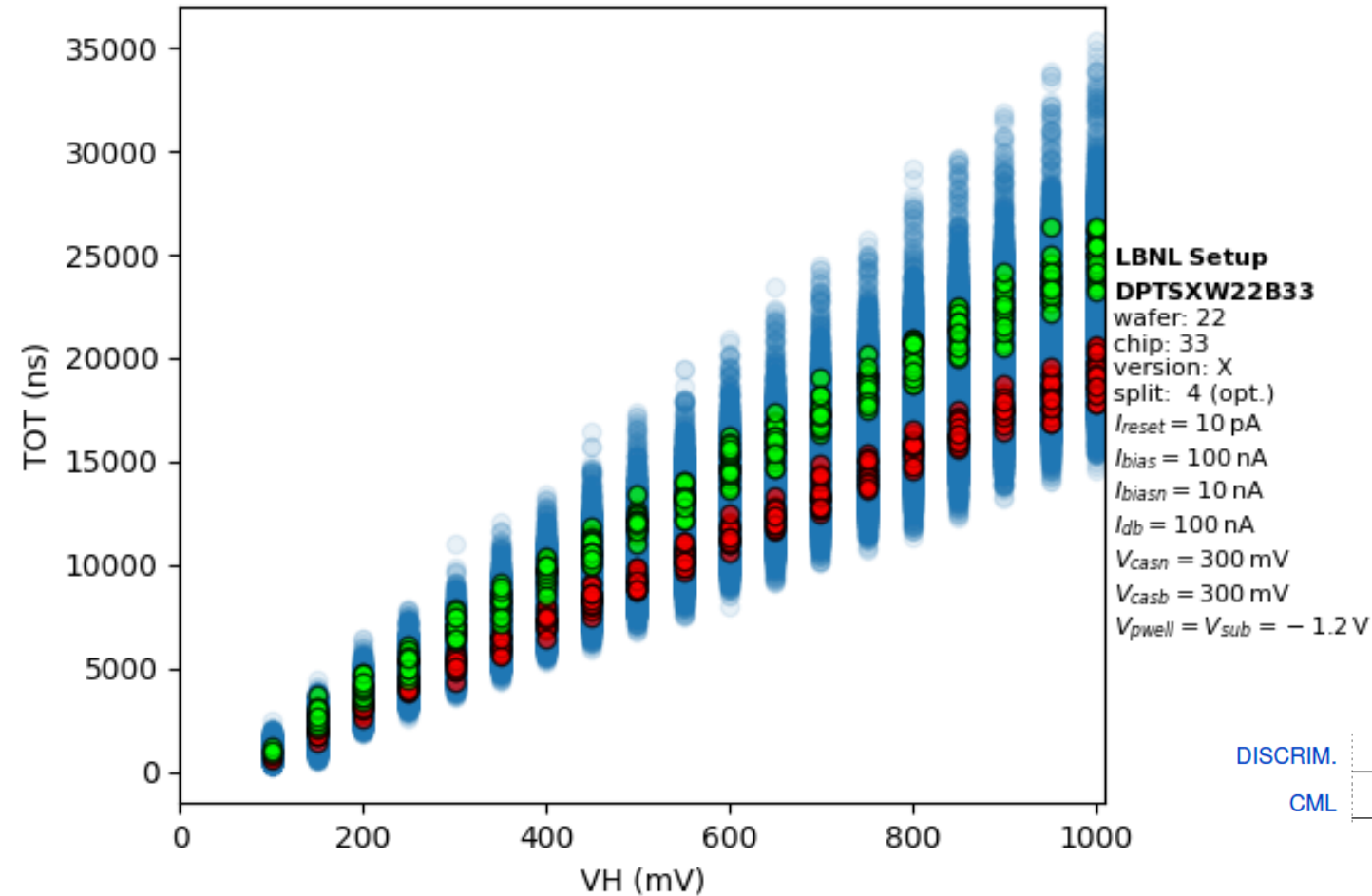


**We can control the threshold by adjusting the VCASB voltage.**



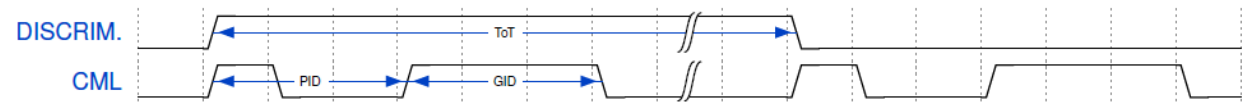
# Time-over-threshold (ToT)

Pix 14 and Pix 21 7

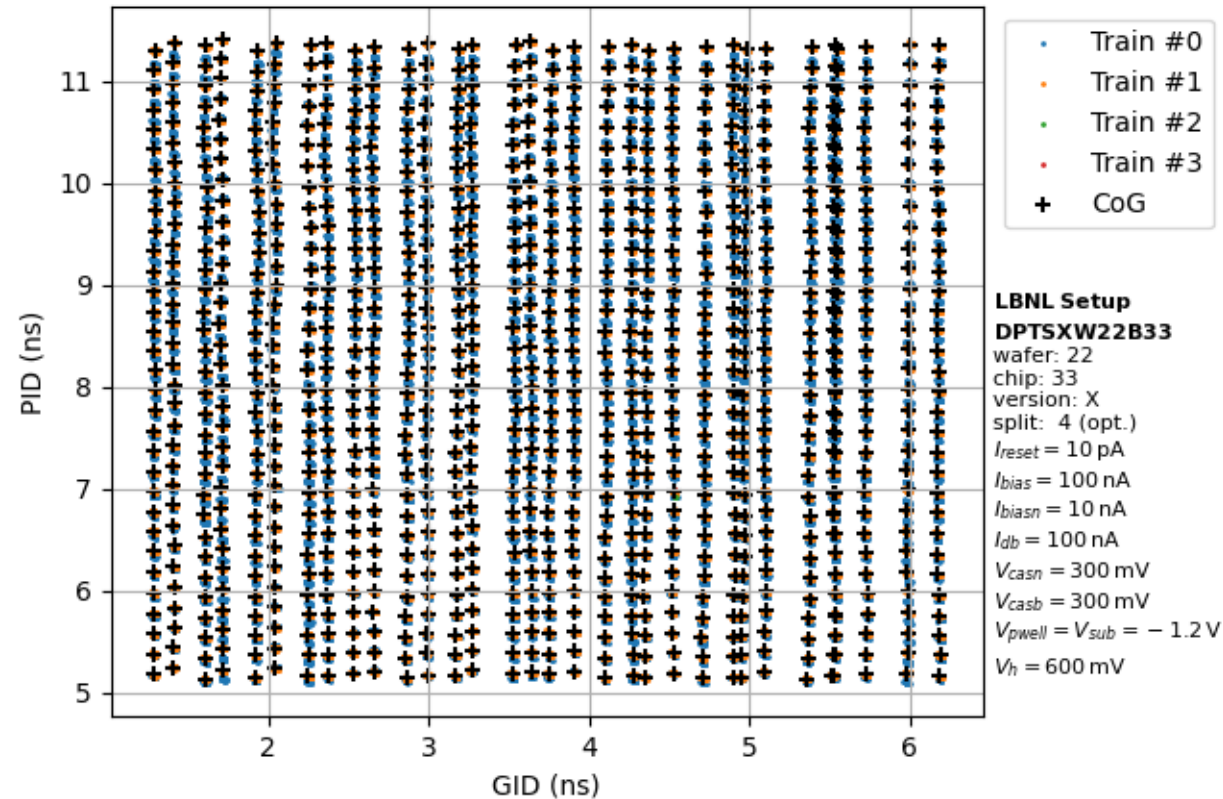


The ToT increases linearly with the total collected (injected) charge.

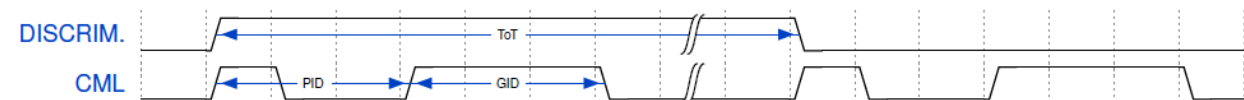
We observe a large pixel-to-pixel variation, which we hope to understand. See next talk by Oscar!



# Pixel position decoding

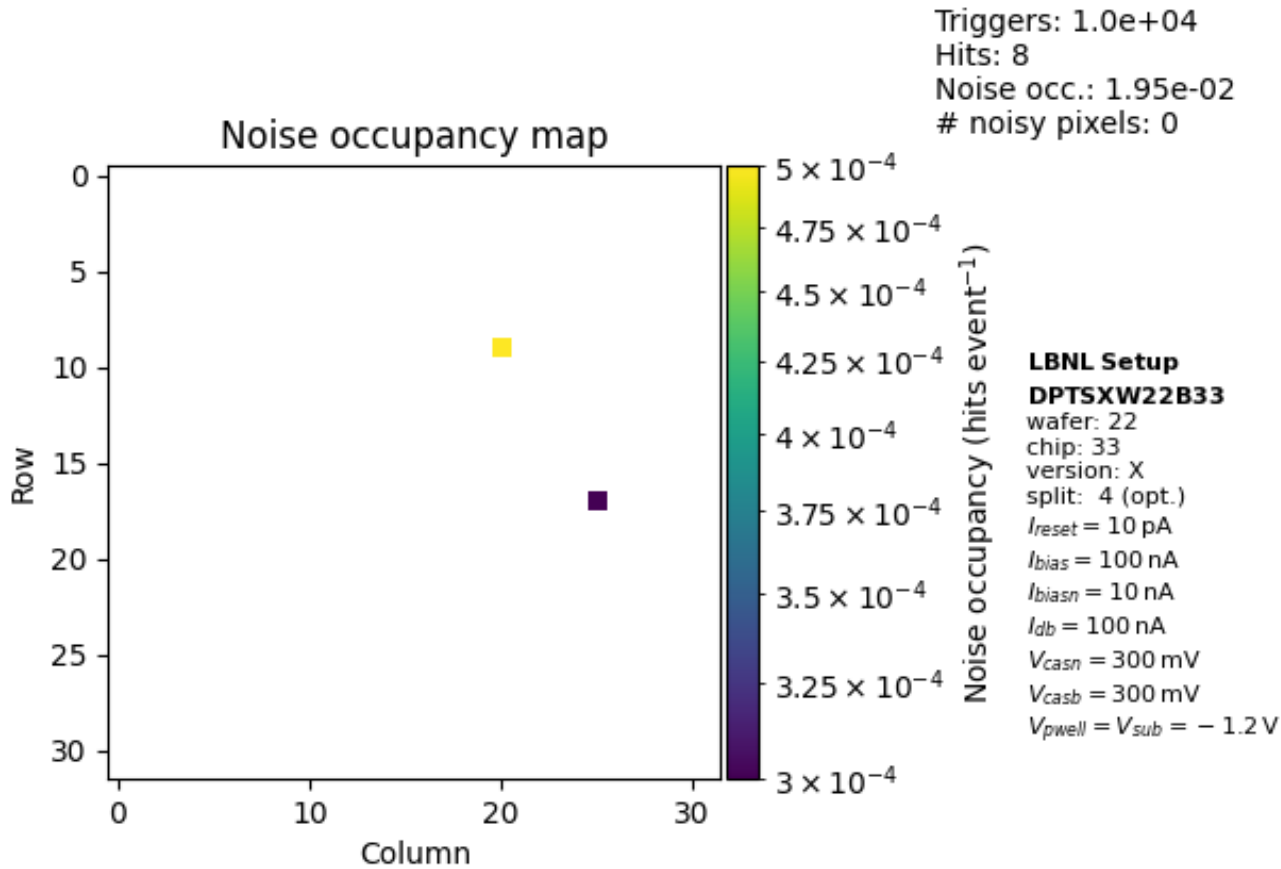


In the case where we don't inject charge, we need a way to decode the pixel that fired based on the CML signal. This is encoded in the PID and GID times.





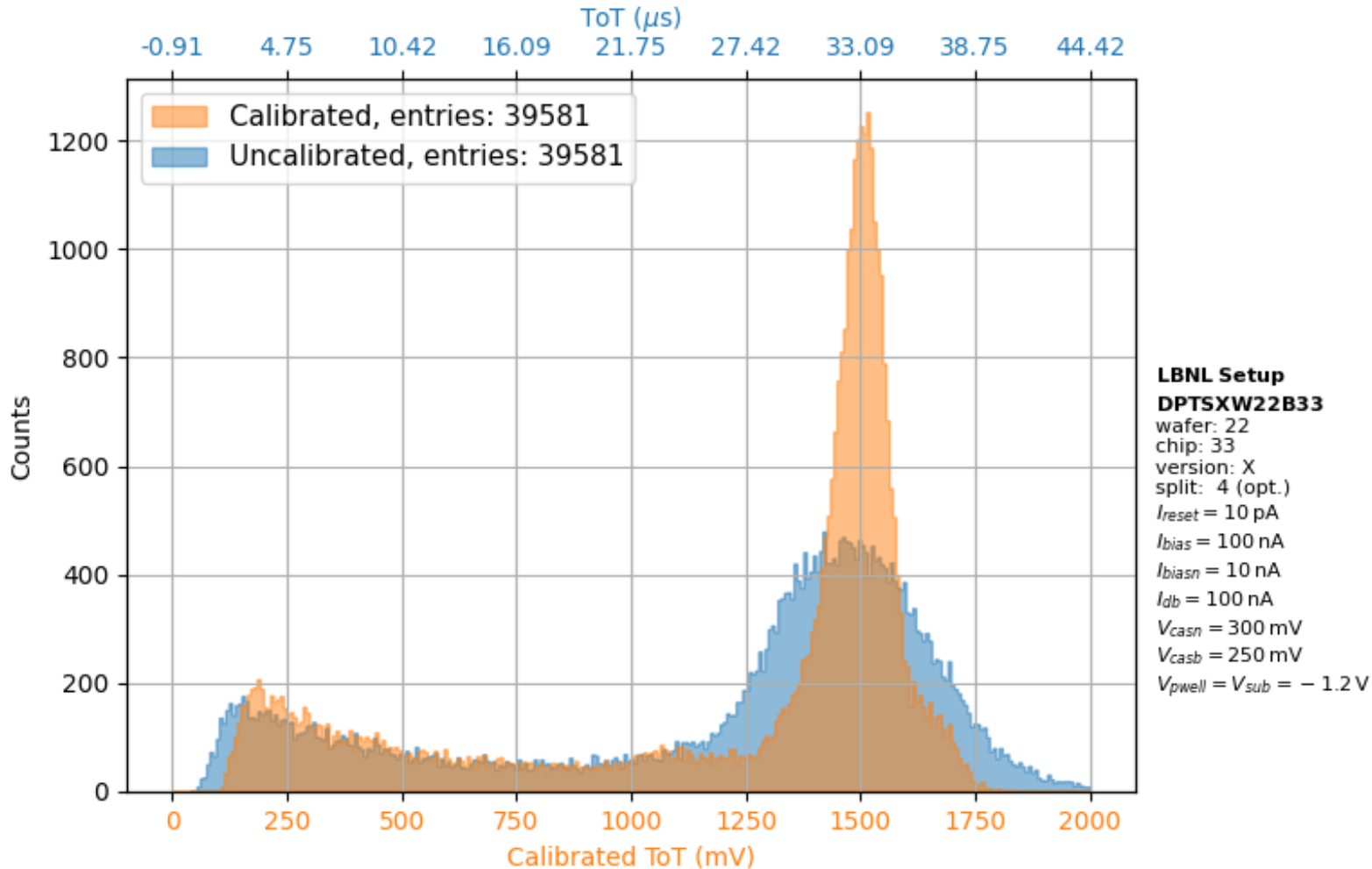
# Fake hit rate check



The fake hit rate measures the number of hits seen in the absence of external stimuli. That is, we trigger on a clock and look for any pixel signals.

$$\begin{aligned}
 \text{Noise Occ.} &= \\
 &= \frac{\text{Hits}}{(\text{Triggers} \times \text{Pixels} \times \text{scope capture time})} = \\
 &= \frac{8}{(10,000 \times 1024 \times 40 \text{ us})} = \\
 &= 0.0195 \text{ per pixel per s}
 \end{aligned}$$

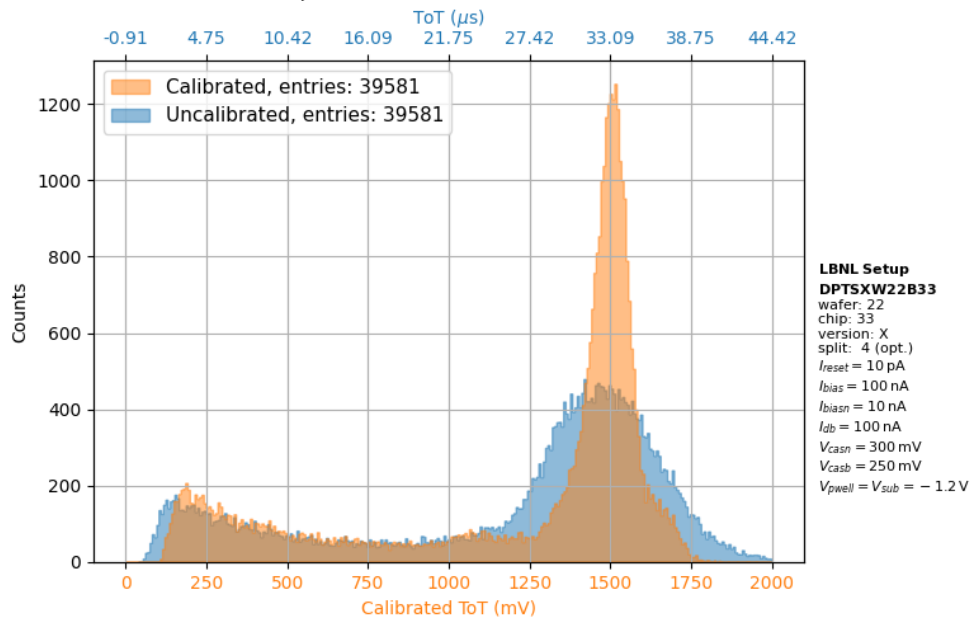
# $^{55}\text{Fe}$ source data



Collected 100k triggers with a  $^{55}\text{Fe}$  source. After requiring events with a single pixel and applying some other cuts, about 40k events remain.

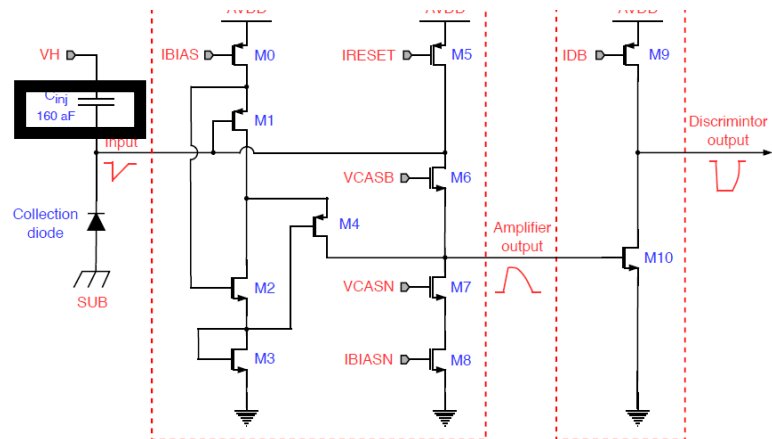
The main peak should be the K-alpha X-ray at 5.9 keV. Since it takes 3.6 eV to create an electron-hole pair in silicon, we would expect this peak to be at 1640 electrons. However, we see the peak at  $\sim 1510$  electrons. Why do we see this shift?

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**The ToT calibration is based on the injected charge (set by the voltage  $V_H$ ). The  $C_{inj}$  capacitance can differ from the design value.**

For 160 aF  $C_{inj}$ , we have  $V_H \text{ (mV)} = Q_{inj} \text{ (e}^-)$ .



# Summary

- We have a working bench setup for the DPTS prototype chip.
- We have done some basic studies with injected charge to test the front-end electronics.
- We have also collected data using and  $^{55}\text{Fe}$  source.
- We are currently focusing on studying the pixel-to-pixel variation of the ToT. See next talk by Oscar!